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Summary

I have over 25 years of leading edge technical experience both as a leader and an individual contributor with a record of highly effective, flawless and prolific execution. My strengths include good communication and analytical skills, breadth of knowledge and ingenuity.

Experience

[18-19] Consultant, Confidential.

- . Physical design methodology for a 7nm Machine Learning SoC. Design of global clock distribution network, spice modeling/simulation and ICC2 implementation. Setup custom compiler schematic and netlisting environment. Characterize PVT sensitivity of level shifters with spice simulations. Set up Redhawk seascape flow for EM/IR. Own a million gate low voltage design for place and route.

[16-17] Consultant, ZGlue Inc.

- . Physical design methodology and netlist-to-gds flow development in tcl using Cadence toolset. Also Assura physical verification and logical equivalence (lec) flows.
- . Hierarchical implementation of an instance array design including floorplanning, power grid, pin placement, place and route, logical equivalence and physical verification.
- . Abstract generation of analog macros and hierarchical instance to allow for through the block routing.
- . Mixed-signal custom CAD support including SKILL programming
- . Setup Virtuoso QRC extraction flow for full chip STA, set up and run full chip STA with Tempus, set up and run full chip LEC with Conformal. Silicon success.

[15-16] Machine Learning/Software Engineer

- . Data Science/Machine Learning/Programming
- . Swift iOS Programming

[13-14] Qualcomm Technologies, Senior Staff Engineer

Top level floorplan, power grid with multiple power domains, using CPF/UPF for a mixed signal design, automated floorplan generation with Tcl. Wrote power intent CPF from scratch. Full chip formal (LEC) and low power (CLP) verification using Cadence tools. Apache Redhawk EM/IR debug and fixes. My leadership enabled a rare ahead of schedule tapeout. Silicon success (WCD9335).

[12-13] Cadence Design Systems, Staff Application Engineer

Developed complete, automated rtl2gds flow (14nm/finFET) using Cadence tools. Using the same, implemented an ARM A9 design @ 2.4GHz. Implemented a 28nm DDR-PHY IP for tapeout.

[11-12] Sandforce Inc., Principal Engineer

- . Developed a 40 nm automated and optimized, tapeout ready, Cadence based implementation flow.
- . Wrote Tcl scripts for a correct by construction, tunable flow used for all blocks.
- . Developed automated, tapeout ready, STA setup using Primetime-SI using Tcl/Perl scripts.
- . Implemented several large blocks at tapeout quality using the above flow ; the resulting GDSII were timing, LEC, LVS/DRC clean. Silicon success.
- . Helped grow the size and capability of the physical design team and lead technical direction.

[08-11] Contractor/Engineer @(multiple)

- . Setup 40nm Cadence based, automated, tapeout ready, block level implementation flow.
- . Hierarchical physical implementation flow in 65nm technology using Cadence.
- . Telecom ASIC: Implementation of two large blocks using Magma. Silicon Success.
- . 65nm WiFi ASIC: Implementation of large block using Magma. Silicon Success.
- . 65nm WiFi ASIC: Full chip EM/IR signoff using Apache-Redhawk. Silicon Success.

[06-08] Teranetics, Principal Engineer

130nm/65nm 10GBASE-T PHY ASIC: Implement many large blocks, some using x-route. Automate implementation, static timing analysis, logical equivalence and physical verification flows. Power estimation; power reduction using special cells. Silicon Success.

[04-06] Airgo Networks, Physical Design Manager

Multiple WiFi ASICs: Implement many blocks using Magma. Automate PTSI STA, formal, Calibre PV flows. Full chip EM/IR signoff using Apache-Redhawk. Tapeout signoff/jobview. ECOs, I/O Spice sims, IP integration, Methodology, project management. Silicon success.

[01-04] Transmeta, senior Member, Technical Staff

1.2/1.8GHz Efficeon CPUs: Implement Hypertransport PnR blocks; Register File design. ECOs. Setup latch compatible STA flow. Array and noise methodologies. Silicon Success.

[99-01] Sun Microsystems, Member, Technical Staff

- UltraSparc V CPU: CAM Register File, Custom logic circuit design
- 1.2GHz UltraSparc III CPU: Port a dozen 130nm dynamic circuit blocks, including adders up to 64-bits, from 180nm to 130nm. Silicon success.

[97-99] Intel Corporation, Design Engineer

- 833MHz Pentium III Xeon CPU: High speed dynamic circuit design for L2\$ ECC, L2\$ STA/EM/IR verification. Silicon success.
- 600 MHz Pentium III CPU : GTL I/O circuit design. Silicon success.

[94-97] ST Microelectronics, Design Engineer

Circuit Design of 32kx8, 128kx8 SRAMs. Silicon success. CAD setup. Reverse engineer a register file and re-implement, verify functionality using verilog switch level simulation. Silicon success.

Education

I was the best student in my class for all seven years of college level education, including four at India's premium engineering institution.

[1989-93] M.Engg., Electrical Comm, Indian Institute of Science.

First class with distinction. Alumni medal, Best Student, 1990-93

[1986-89] B.Sc., Physics, Delhi University.

First class with distinction, Gold medal, Best Student: 1987/88/89.